

## Lonten N-channel 100V, 80A, 8mΩ Power MOSFET

<p><b>Description</b>                  These N-Channel enhancement mode power field effect transistors are using split gate trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.</p> <p><b>Features</b></p> <ul style="list-style-type: none"> <li>◆ 100V,80A,<math>R_{DS(ON),max}=8m\Omega@V_{GS}=10V</math></li> <li>◆ Improved dv/dt capability</li> <li>◆ Fast switching</li> <li>◆ 100% EAS Guaranteed</li> <li>◆ Green device available</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>◆ Motor Drives</li> <li>◆ UPS</li> <li>◆ DC-DC Converter</li> </ul>	<p><b>Product Summary</b></p> <table style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 60%;"><math>V_{DSS}</math></td> <td>100V</td> </tr> <tr> <td><math>R_{DS(on),max}@V_{GS}=10V</math></td> <td>8mΩ</td> </tr> <tr> <td><math>I_D</math></td> <td>80A</td> </tr> </table> <p><b>Pin Configuration</b></p> <div style="text-align: center;"> <p>TO-220FB      TO-220MF</p> <p>TO-263      TO-262</p> </div> <div style="text-align: right; margin-top: 10px;"> <p>N-Channel MOSFET</p> </div>	$V_{DSS}$	100V	$R_{DS(on),max}@V_{GS}=10V$	8mΩ	$I_D$	80A
$V_{DSS}$	100V						
$R_{DS(on),max}@V_{GS}=10V$	8mΩ						
$I_D$	80A						

### Absolute Maximum Ratings $T_C = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	100	V
Continuous drain current ( $T_C = 25^\circ C$ )	$I_D$	80	A
Continuous drain current ( $T_C = 100^\circ C$ )		60	A
Pulsed drain current <sup>(note 1)</sup>	$I_{DM}$	320	A
Gate-Source voltage	$V_{GSS}$	$\pm 20$	V
Avalanche energy, single pulse <sup>(note 2)</sup>	$E_{AS}$	110	mJ
Power Dissipation ( $T_C = 25^\circ C$ ) TO-220FB/TO-263-2L	$P_D$	150	W
Power Dissipation ( $T_C = 25^\circ C$ ) TO-220MF	$P_D$	48	W
Storage Temperature Range	$T_{STG}$	-55 to +150	$^\circ C$
Operating Junction Temperature Range	$T_J$	-55 to +150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case TO-220FB/TO-263-2L	$R_{\theta JC}$	0.83	$^\circ C/W$
Thermal Resistance, Junction-to-Case TO-220MF		2.6	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient TO-220FB/TO-263-2L	$R_{\theta JA}$	62	$^\circ C/W$
Thermal Resistance, Junction-to-Case TO-220MF		80	$^\circ C/W$

**Package Marking and Ordering Information**

Device	Device Package	Marking
LSGC10R080W3	TO-220FB	LSGC10R080W3
LSGD10R080W3	TO-220MF	LSGD10R080W3
LSGE10R080W3	TO-263	LSGE10R080W3
LSGF10R080W3	TO-262	LSGF10R080W3

**Electrical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static characteristics</b>						
Drain-source breakdown voltage	$BV_{DSS}$	$V_{GS}=0\text{ V}, I_D=250\mu\text{A}$	100	---	---	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.4	1.8	2.2	V
Drain-source leakage current	$I_{DSS}$	$V_{DS}=100\text{V}, V_{GS}=0\text{V}, T_J = 25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{DS}=80\text{V}, V_{GS}=0\text{V}, T_J = 125^\circ\text{C}$	---	---	10	$\mu\text{A}$
Gate leakage current, Forward	$I_{GSSF}$	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	---	---	100	nA
Gate leakage current, Reverse	$I_{GSSR}$	$V_{GS}=-20\text{ V}, V_{DS}=0\text{ V}$	---	---	-100	nA
Drain-source on-state resistance (note 3)	$R_{DS(on)}$	$V_{GS}=10\text{ V}, I_D=50\text{ A}$	---	6.8	8	m $\Omega$
Drain-source on-state resistance (note 3)		$V_{GS}=4.5\text{ V}, I_D=40\text{ A}$	---	8.3	10	m $\Omega$
Forward transconductance	$g_{fs}$	$V_{DS}=5\text{ V}, I_D=50\text{A}$	---	112	---	S
<b>Dynamic characteristics</b>						
Input capacitance	$C_{iss}$	$V_{DS} = 50\text{ V}, V_{GS} = 0\text{ V},$ $F = 1\text{MHz}$	---	2630	---	pF
Output capacitance	$C_{oss}$		---	453	---	
Reverse transfer capacitance	$C_{rss}$		---	36	---	
Turn-on delay time (note 3,4)	$t_{d(on)}$	$V_{DD} = 50\text{V}, V_{GS}=10\text{V}, I_D = 50\text{A}$	---	10.5	---	ns
Rise time (note 3,4)	$t_r$		---	63	---	
Turn-off delay time (note 3,4)	$t_{d(off)}$		---	30	---	
Fall time (note 3,4)	$t_f$		---	96	---	
Gate resistance	$R_g$	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, F=1\text{MHz}$	---	1.1	---	$\Omega$
<b>Gate charge characteristics</b>						
Gate to source charge (note 3,4)	$Q_{gs}$	$V_{DS}=50\text{ V}, I_D=50\text{A},$ $V_{GS}= 10\text{ V}$	---	10.2	---	nC
Gate to drain charge (note 3,4)	$Q_{gd}$		---	6.6	---	
Gate charge total (note 3,4)	$Q_g$		---	45	---	
<b>Drain-Source diode characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0\text{ V},$ Force Current	---	---	80	A
Pulsed Source Current (note 3)	$I_{SM}$		---	---	320	A
Diode Forward Voltage (note 3)	$V_{SD}$	$V_{GS}=0\text{V}, I_S=50\text{A}, T_J=25^\circ\text{C}$	---	0.95	1.3	V
Reverse Recovery Time	$t_{rr}$	$I_S=50\text{A}, di/dt=100\text{A}/\mu\text{s},$ $T_J=25^\circ\text{C}$	---	65	---	ns
Reverse Recovery Charge	$Q_{rr}$		---	104	---	nC

**Notes:**

1: Repetitive Rating: Pulse width limited by maximum junction temperature.

2:  $V_{DD}=50\text{V}, V_{GS}=10\text{V}, L=0.5\text{mH}, I_{AS}=21\text{A}, R_G=25\Omega,$  Starting  $T_J=25^\circ\text{C}$ .

3: Pulse Test: Pulse Width  $\leq 300\mu\text{s},$  Duty Cycle  $\leq 2\%$ .

4: Essentially independent of operating temperature.

**Electrical Characteristics Diagrams**

Figure 1. Typ. Output Characteristics

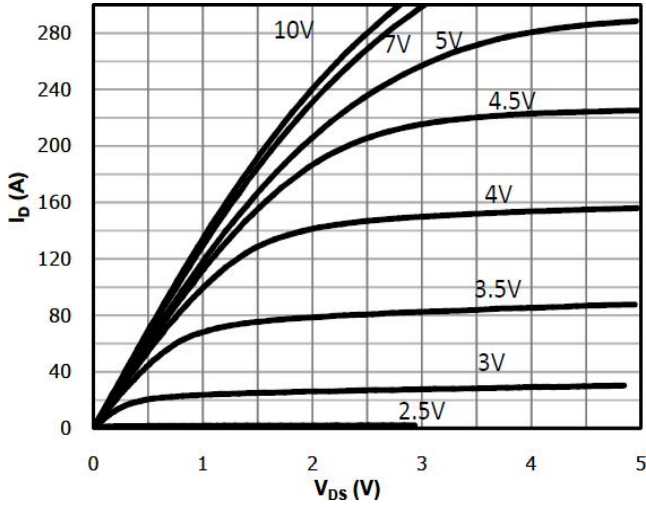


Figure 3. Capacitance Characteristics

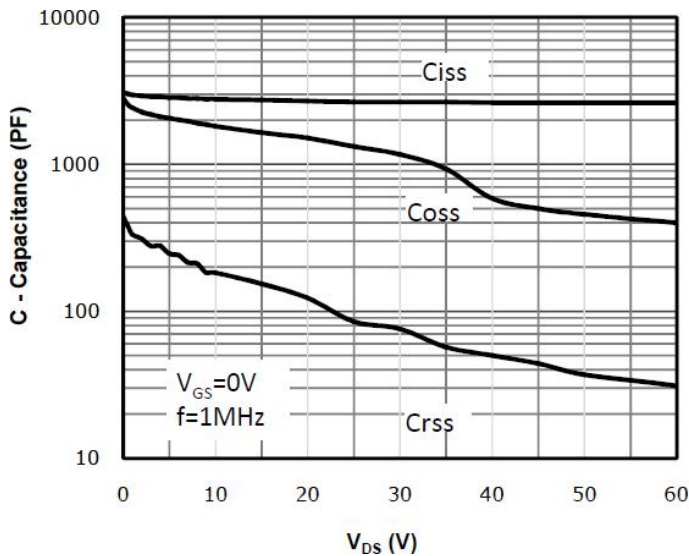


Figure 5. Body-Diode Characteristics

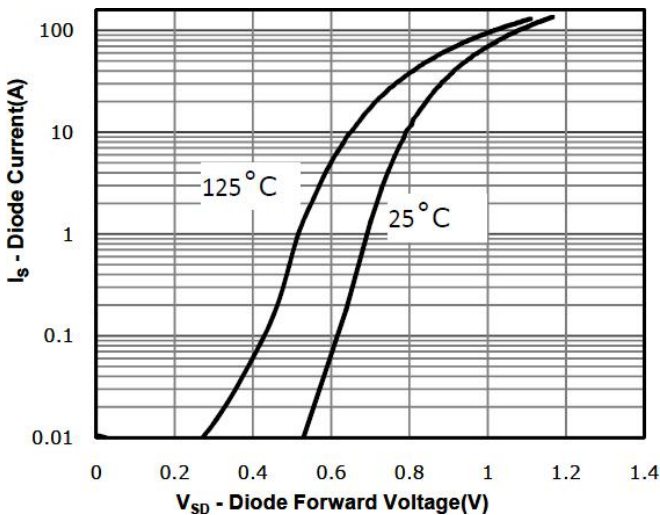


Figure 2. Transfer Characteristics

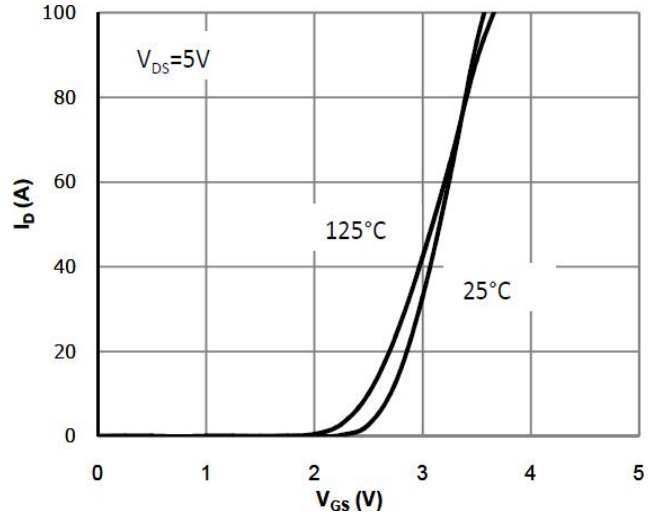


Figure 4. Gate Charge Waveform

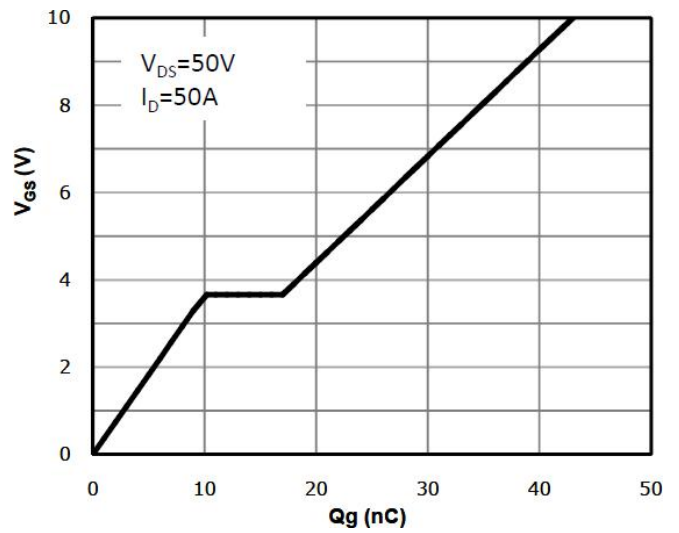


Figure 6. Rds(on)-Drain Current

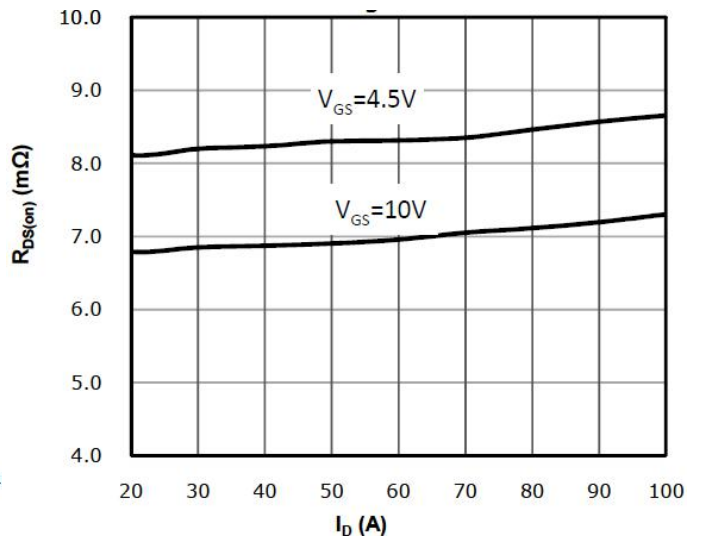


Figure 7. Rds(on)-Junction Temperature(°C)

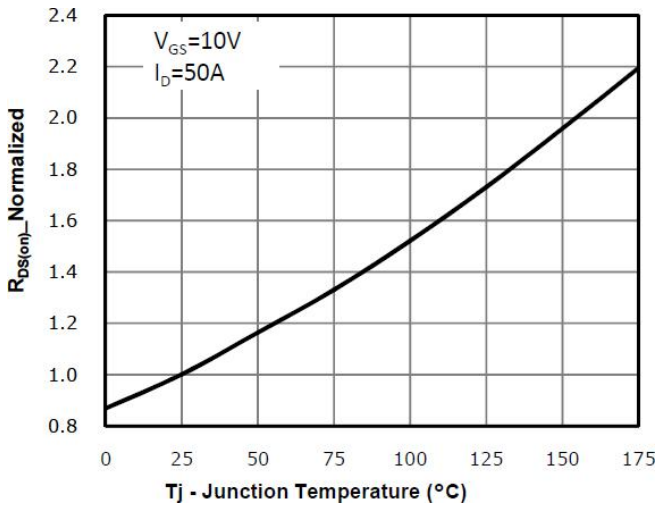


Figure 8. Maximum Safe Operating Area

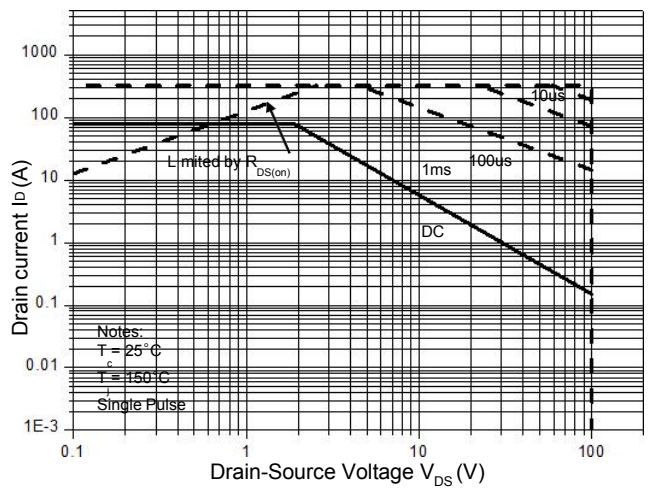
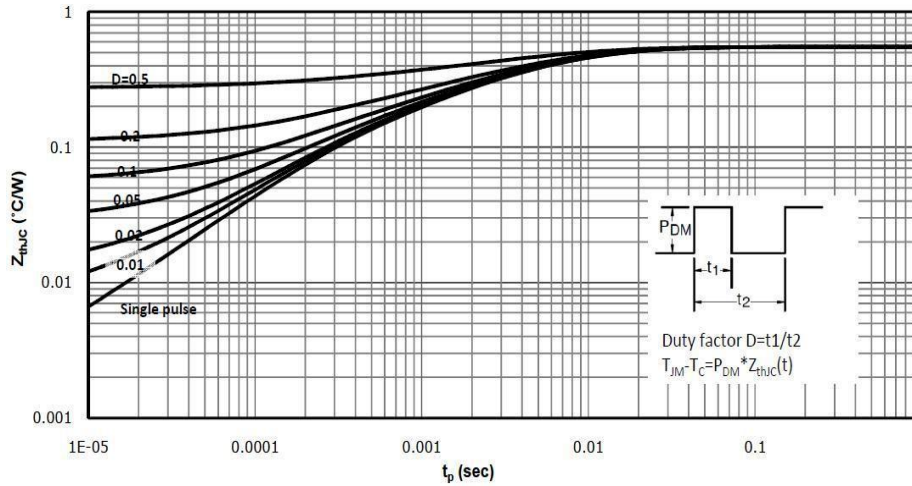


Figure 9. Normalized Maximum Transient Thermal Impedance (RthJC)



**Test Circuit & Waveform**

Figure 8. Gate Charge Test Circuit & Waveform

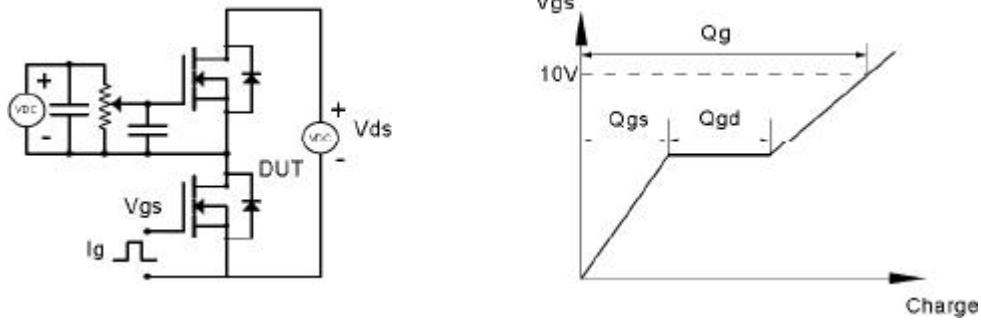


Figure 9. Resistive Switching Test Circuit & Waveforms

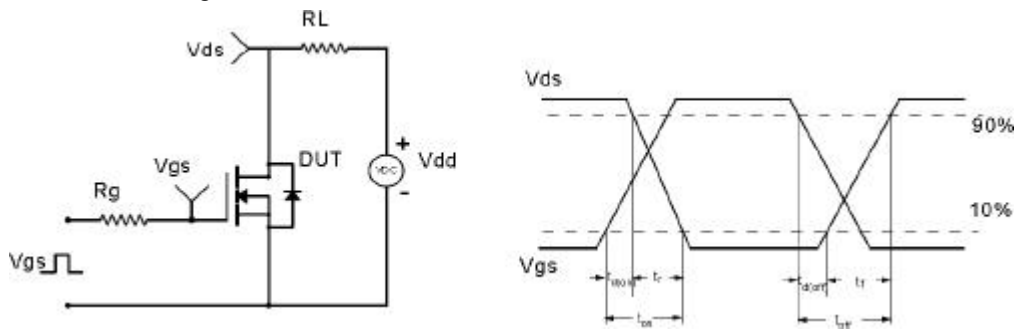


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

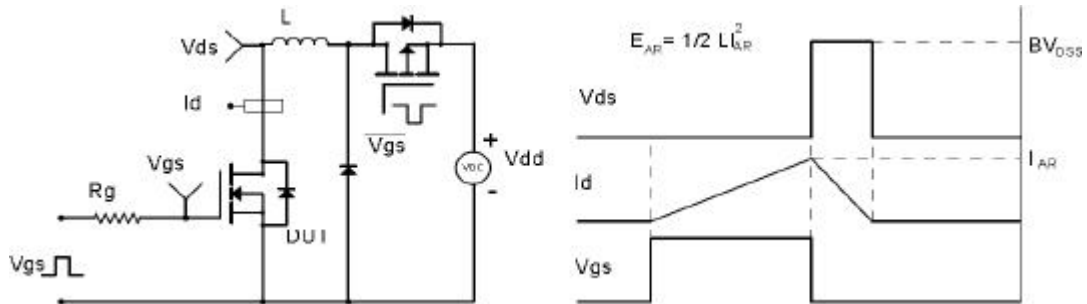
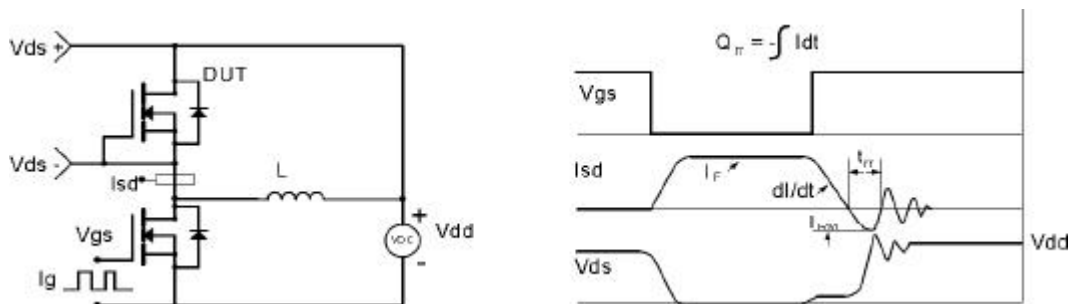
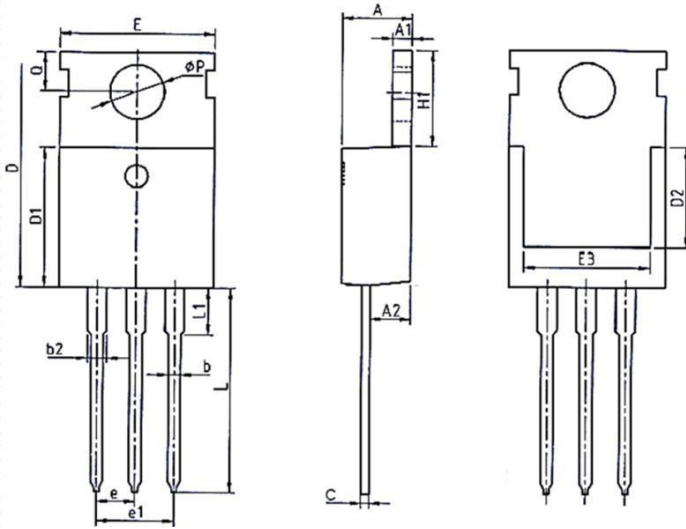


Figure 11. Diode Recovery Circuit & Waveform

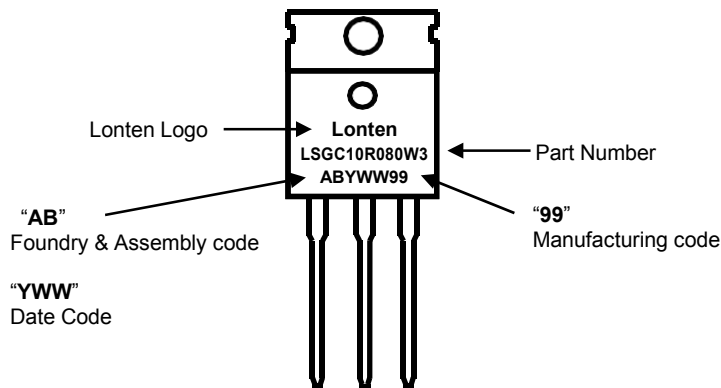


**Mechanical Dimensions for TO-220**

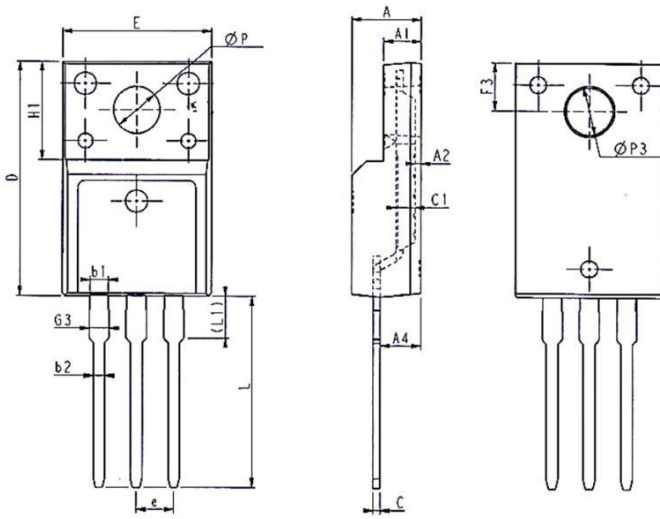


COMMON DIMENSIONS						
SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.37	4.57	4.70	0.172	0.180	0.185
A1	1.25	1.30	1.40	0.049	0.051	0.055
A2	2.20	2.40	2.60	0.087	0.094	0.102
b	0.70	0.80	0.95	0.028	0.031	0.037
b2	1.17	1.27	1.47	0.046	0.050	0.058
c	0.45	0.50	0.60	0.018	0.020	0.024
D	15.10	15.60	16.10	0.594	0.614	0.634
D1	8.80	9.10	9.40	0.346	0.358	0.370
D2	5.50	-	-	0.217	-	-
E	9.70	10.00	10.30	0.382	0.394	0.406
E3	7.00	-	-	0.276	-	-
e	2.54BCS			0.1BSC		
e1	5.08BCS			0.2REF		
H1	6.25	6.50	6.85	0.246	0.256	0.270
L	12.75	13.50	13.80	0.502	0.531	0.543
L1	-	3.10	3.40	-	0.122	0.134
ØP	3.40	3.60	3.80	0.134	0.142	0.150
Q	2.60	2.80	3.00	0.102	0.110	0.118

**TO-220 Part Marking Information**

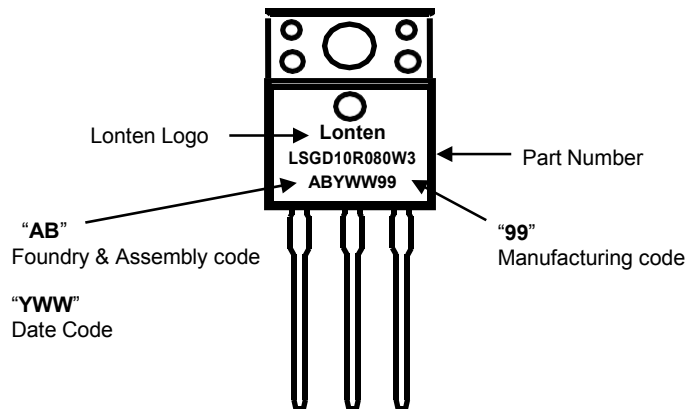


**Mechanical Dimensions for TO-220MF**

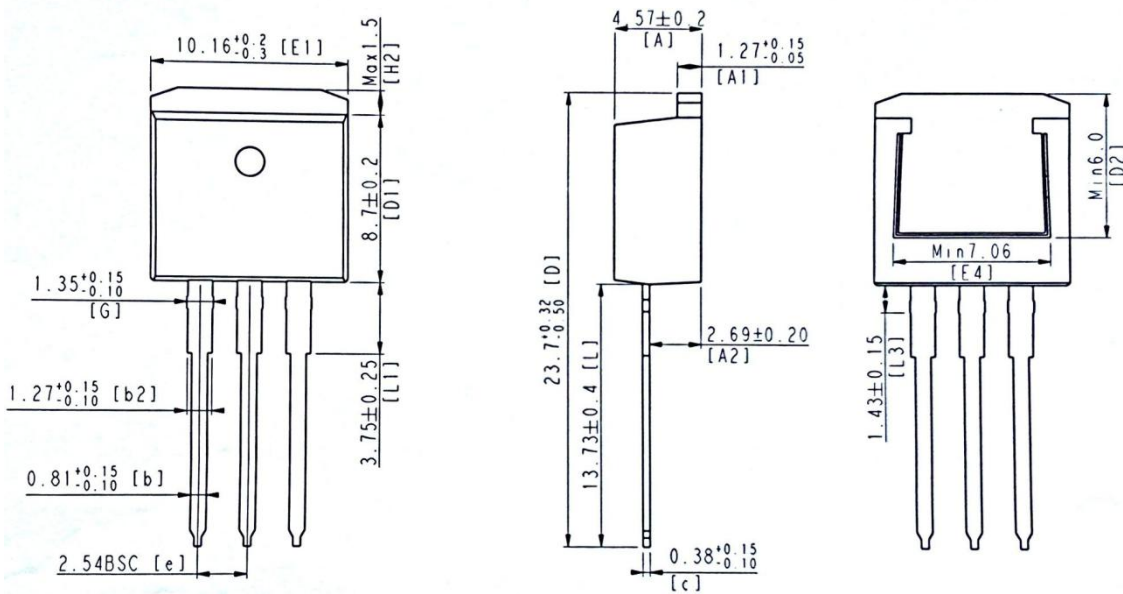


COMMON DIMENSIONS						
SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
E	9.96	10.16	10.36	0.392	0.400	0.408
A	4.50	4.70	4.90	0.177	0.185	0.193
A1	2.34	2.54	2.74	0.092	0.100	0.108
A2	0.30	0.45	0.60	0.012	0.018	0.024
A4	2.56	2.76	2.96	0.101	0.109	0.117
c	0.40	0.50	0.65	0.016	0.020	0.026
c1	1.20	1.30	1.35	0.047	0.051	0.053
D	15.57	15.87	16.17	0.613	0.625	0.637
H1	6.70REF			0.264REF		
e	2.54BSC			0.1BSC		
L	12.68	12.98	13.28	0.499	0.511	0.523
L1	2.88	3.03	3.18	0.113	0.119	0.125
ØP	3.03	3.18	3.38	0.119	0.125	0.133
ØP3	3.15	3.45	3.65	0.124	0.136	0.144
F3	3.15	3.30	3.45	0.124	0.130	0.136
G3	1.25	1.35	1.55	0.049	0.053	0.061
b1	1.18	1.28	1.43	0.046	0.050	0.056
b2	0.70	0.80	0.95	0.028	0.031	0.037

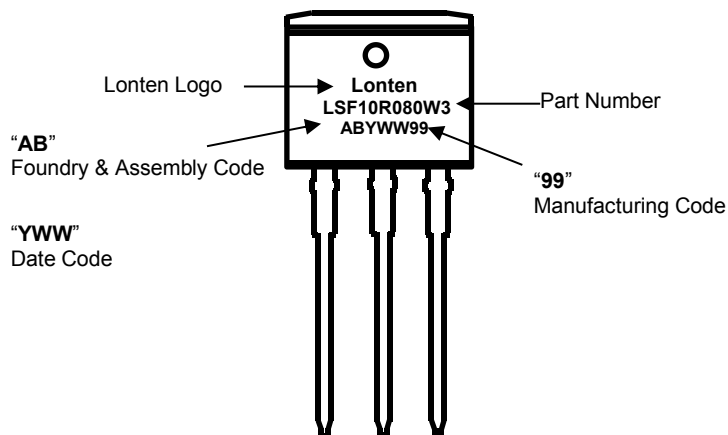
**TO-220MF Part Marking Information**



### Mechanical Dimensions for TO-262

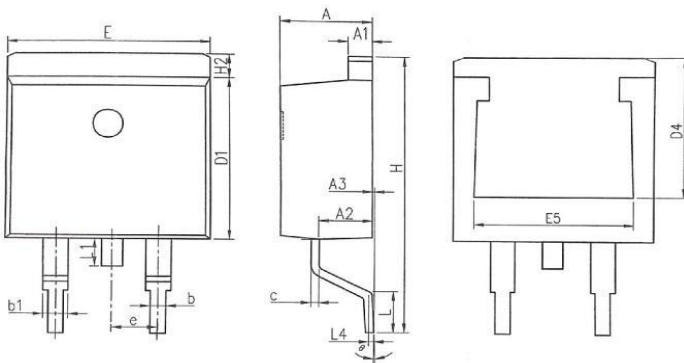


### TO-262 Part Marking Information



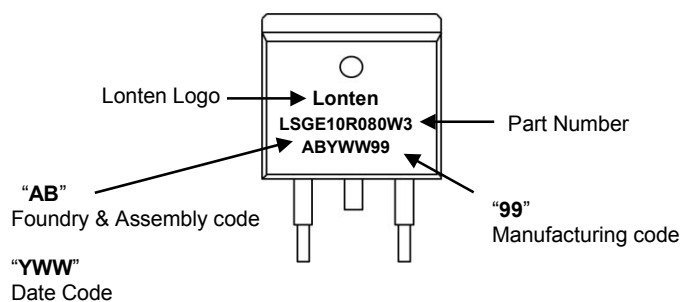


## TO-263 PACKAGE INFORMATION



COMMON DIMENSIONS						
SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.37	4.57	4.77	0.172	0.180	0.188
A1	1.22	1.27	1.42	0.048	0.050	0.056
A2	2.49	2.69	2.89	0.098	0.106	0.114
A3	0.00	0.13	0.25	0.000	0.005	0.010
b	0.70	0.81	0.96	0.028	0.032	0.038
b1	1.17	1.27	1.47	0.046	0.050	0.058
c	0.30	0.38	0.53	0.012	0.015	0.021
D1	8.50	8.70	8.90	0.335	0.343	0.350
D4	6.60	—	—	0.260	—	—
E	9.86	10.16	10.36	0.388	0.400	0.408
E5	7.06	—	—	0.278	—	—
e	2.54 BSC			0.100 BSC		
H	14.70	15.10	15.50	0.579	0.594	0.610
H2	1.07	1.27	1.47	0.042	0.050	0.058
L	2.00	2.30	2.60	0.079	0.091	0.102
L1	1.40	1.55	1.70	0.055	0.061	0.067
L4	0.25 BSC			0.010 BSC		
θ	0°	5°	9°	0°	5°	9°

## TO-263 Part Marking Information



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